



E-Song America, Inc.

100%
RoHS Compliant
Products

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THERMAL INTERFACE PAD: THEA750

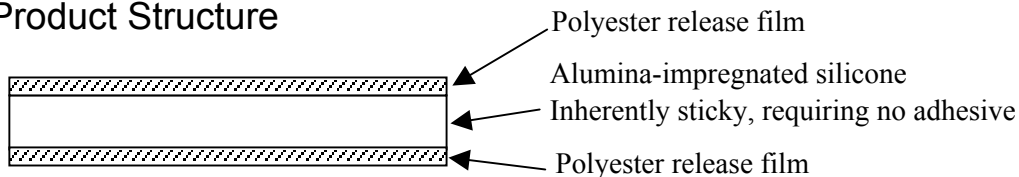
Characteristic

This product is made of conformable, elastic polymer pad filled with Alumina filler providing excellent heat conductivity. It fills air voids between PC boards and heat sink or metal chassis (heat spreader) with high stackup tolerances. Flame retardant UL94V0 and good electrical

Application

- Areas where heat needs to be transferred away to the frame chassis or other type of heat spreader
- Between a CPU and a heat spreader
- Between a CD ROM drive and a heat spreader
- Between a semiconductor and heat sink
- Replacement for messy grease
- Available in custom sizes and die-cut shapes/sizes

Product Structure



Technical data

ITEM		VALUE	TEST METHOD	
Material	Binder	Silicone		
	Filler	Alumina		
	Liners (top and bottom)	Polyester		
Mechanical properties	Thickness (mm)	Silicone pad available	0.5 to 10 ±0.25	ASTM D 1000
		Release film	0.100	
	Standard size (mm)		300 x 300	
	Color	Silicone pad	Gray	Visual
		Release film	Transparent	Visual
	Hardness (Shore OO)		65 ~ 85	ASTM D 2240
Specific gravity (g/cm ³)		3.1	ASTM D 792	
Continuous usage temp. (°C)		-60 ~ +180		
Electrical properties	Dielectric constant		3.4	ASTM D 150
	Dielectric breakdown (kV AC)		>6	ASTM D 149
	Volume resistivity (ohm-meter)		>10 ¹²	ASTM D 257
Thermal conductivity 10psi (w/m.K)		5.0	ASTM D 5470	
Flame Rating		UL94 V0		

